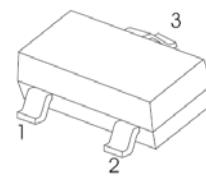


Features

- $V_{DS}(V) = -30V$
- $R_{DS(ON)} < 80m\Omega$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 130m\Omega$ ($V_{GS} = 4.5V$)

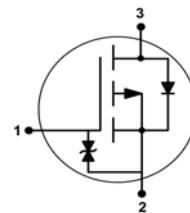
SOT - 23



1. GATE
2. SOURCE
3. DRAIN

Product Summary

- P-channel
- Enhancement mode
- Logic level (4.5V rated)
- ESD protected



Maximum ratings, at $T_j=25^\circ C$, unless otherwise specified

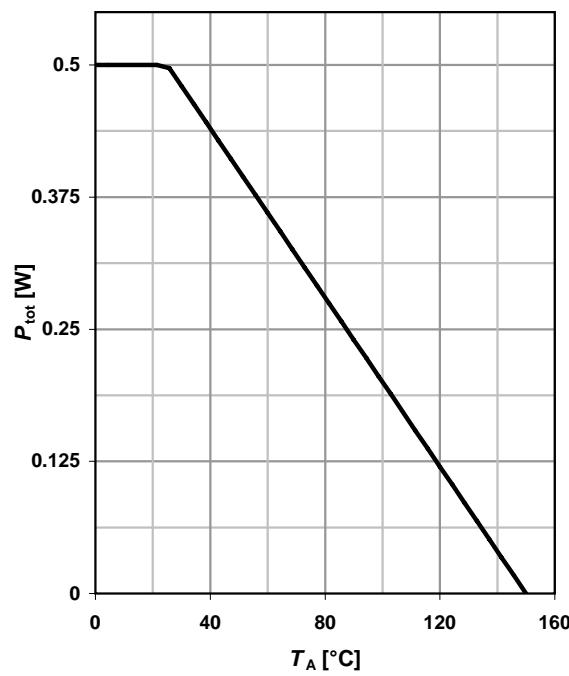
Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_A=25^\circ C$	-2.0	A
		$T_A=70^\circ C$	-1.6	
Pulsed drain current	$I_{D,pulse}$	$T_A=25^\circ C$	-8.0	
Avalanche energy, single pulse	E_{AS}	$I_D=-2 A, R_{GS}=25 \Omega$	-10.7	mJ
Reverse diode dv/dt	dv/dt	$I_D=-2 A, V_{DS}=-16V, di/dt=-200A/\mu s, T_{j,max}=150^\circ C$	6	kV/ μs
Gate source voltage	V_{GS}		± 20	V
Power dissipation ¹⁾	P_{tot}	$T_A=25^\circ C$	0.5	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	$^\circ C$
ESD Class		JESD22-A114 -HBM	2 (2kV to 4kV)	
Soldering Temperature			260 $^\circ C$	$^\circ C$
IEC climatic category; DIN IEC 68-1			55/150/56	$^\circ C$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - ambient	R_{thJA}	minimal footprint ¹⁾	-	-	250	K/W
Electrical characteristics , at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	-	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}$, $I_D=-11\mu\text{A}$	-2.0	-1.5	-1.0	
Drain-source leakage current	I_{DSS}	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ }^\circ\text{C}$	-	-	-1	μA
		$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $T_j=150\text{ }^\circ\text{C}$	-	-	-100	
Gate-source leakage current	I_{GSS}	$V_{GS}=-20\text{V}$, $V_{DS}=0\text{V}$	-	-	-5	μA
Drain-source on-state resistance	$R_{DS(\text{on})}$	$V_{GS}=-4.5\text{ V}$, $I_D=-1.7\text{ A}$	-	88	130	$\text{m}\Omega$
		$V_{GS}=-10\text{ V}$, $I_D=-2\text{ A}$	-	62	80	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(\text{on})\text{max}}$, $I_D=-1.6\text{ A}$		4.6	-	S

¹⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide, 70 μm thick and 20mm long; they are present on both sides of the PCB.

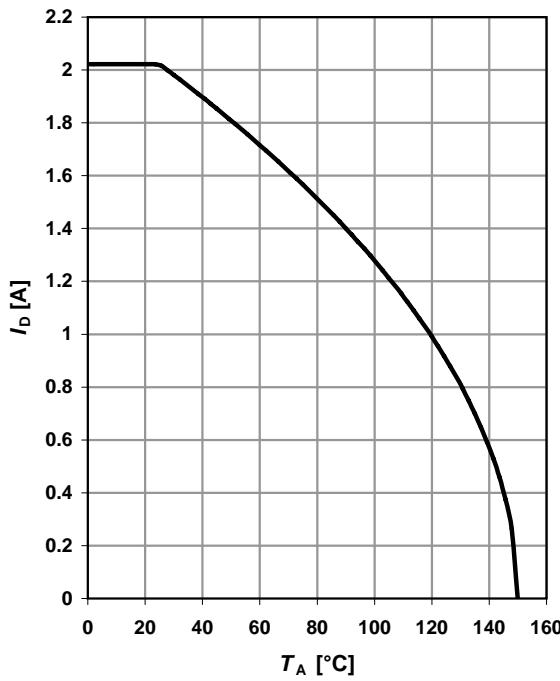
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{GS}=0 \text{ V}, V_{DS}=-15 \text{ V}, f=1 \text{ MHz}$	-	376	500	pF
Output capacitance	C_{oss}		-	196	261	
Reverse transfer capacitance	C_{rss}		-	12	18	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=-15 \text{ V}, V_{GS}=-10 \text{ V}, I_D=-2 \text{ A}, R_G=6 \Omega$	-	5.6	-	ns
Rise time	t_r		-	7.7	-	
Turn-off delay time	$t_{d(off)}$		-	15.3	-	
Fall time	t_f		-	2.8	-	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	$V_{DD}=-15 \text{ V}, I_D=-2 \text{ A}, V_{GS}=0 \text{ to } -10 \text{ V}$	-	-1.2	-	nC
Gate to drain charge	Q_{gd}		-	-0.6	-	
Gate charge total	Q_g		-	-5.0	-	
Gate plateau voltage	$V_{plateau}$		-	-3.1	-	
Reverse Diode						
Diode continuous forward current	I_s	$T_A=25 \text{ }^\circ\text{C}$	-	-	-0.4	A
Diode pulse current	$I_{s,pulse}$		-	-	-8.4	
Diode forward voltage	V_{SD}	$V_{GS}=0 \text{ V}, I_F=-2 \text{ A}, T_j=25 \text{ }^\circ\text{C}$	-	-0.8	-1.1	V
Reverse recovery time	t_{rr}	$V_R=10 \text{ V}, I_F=-2 \text{ A}, dI_F/dt=100 \text{ A}/\mu\text{s}$	-	14	-	ns
Reverse recovery charge	Q_{rr}		-	-5.9	-	nC

Typical Electrical Characteristics



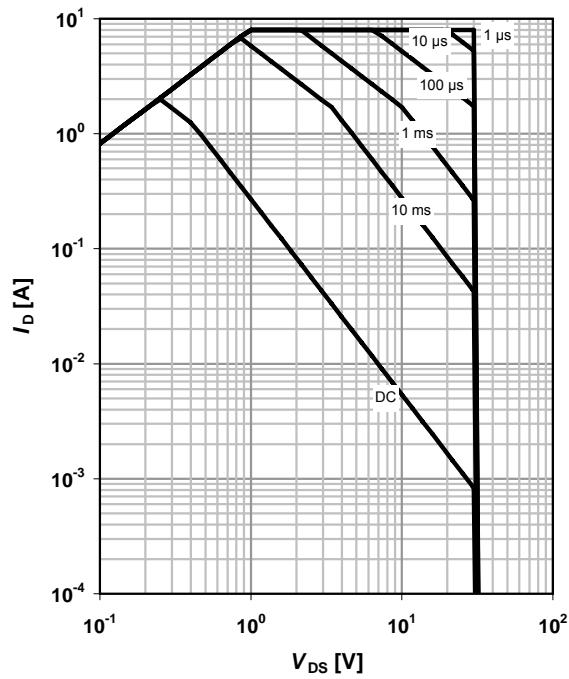
1 Power dissipation

$$P_{\text{tot}}=f(T_A)$$



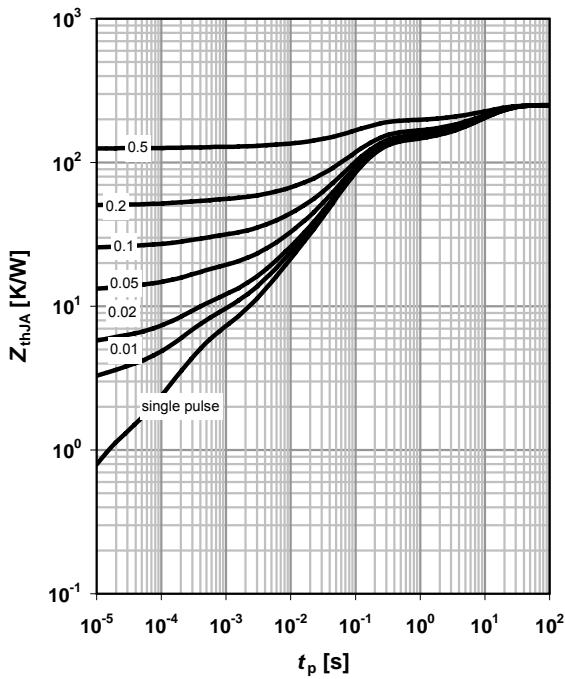
2 Drain current

$$I_D=f(T_A); V_{GS} \geq 10 \text{ V}$$



3 Safe operating area

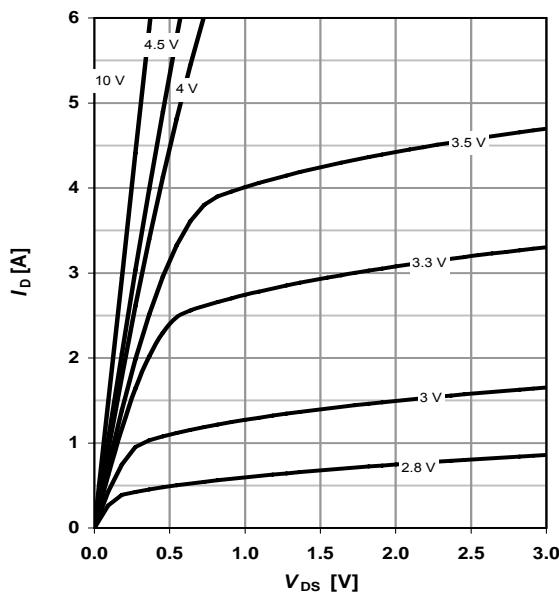
$I_D=f(V_{DS})$; $T_A=25 \text{ }^\circ\text{C}$; $D=0$
parameter: t_p



4 Max. transient thermal impedance

$Z_{\text{thJA}}=f(t_p)$
parameter: $D=t_p/T$

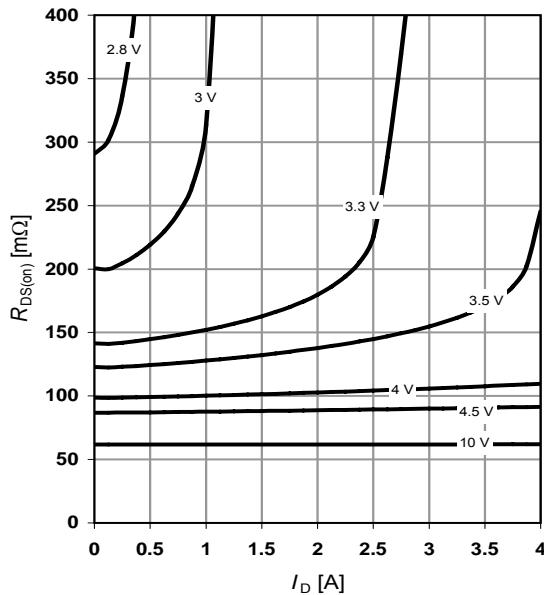
Typical Electrical Characteristics



5 Typ. output characteristics

$I_D=f(V_{DS})$; $T_j=25\text{ }^\circ\text{C}$

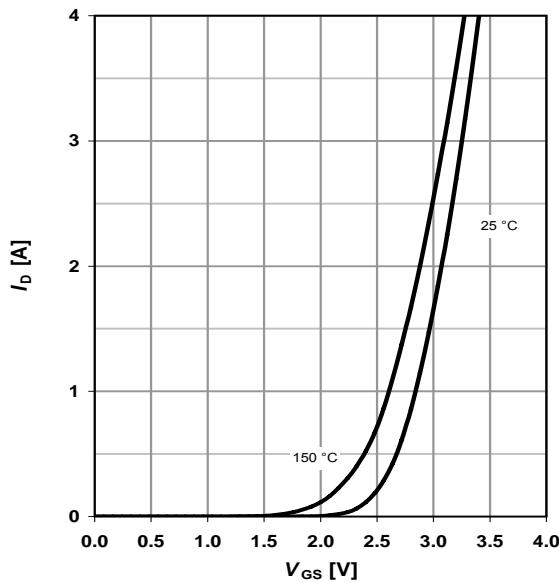
parameter: V_{GS}



6 Typ. drain-source on resistance

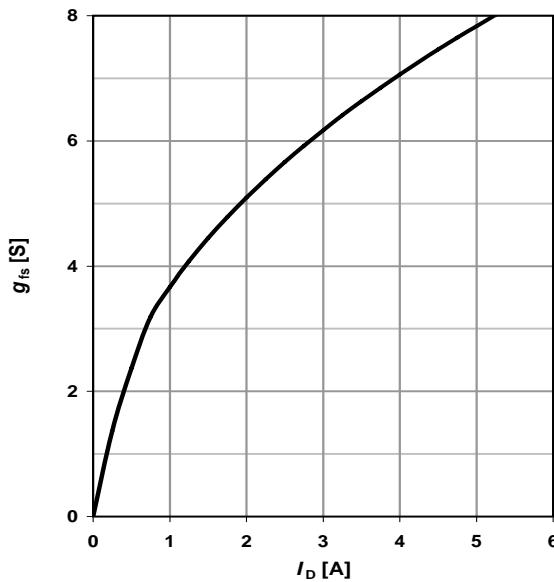
$R_{DS(on)}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$

parameter: V_{GS}



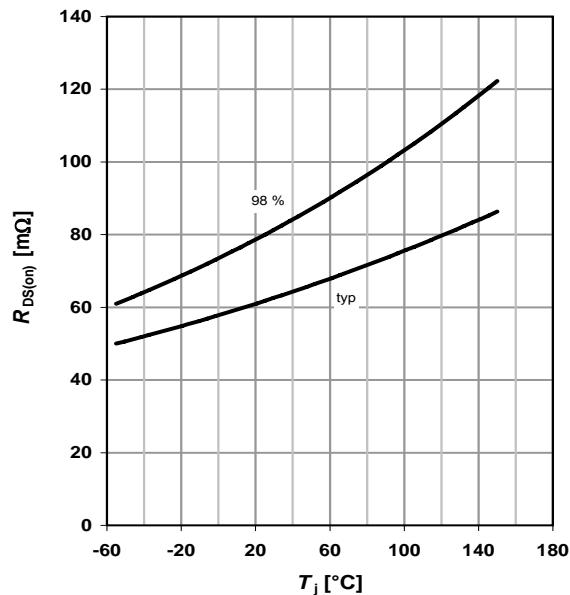
7 Typ. transfer characteristics

$I_D=f(V_{GS})$; $|V_{DS}|>2|I_D|R_{DS(on)max}$

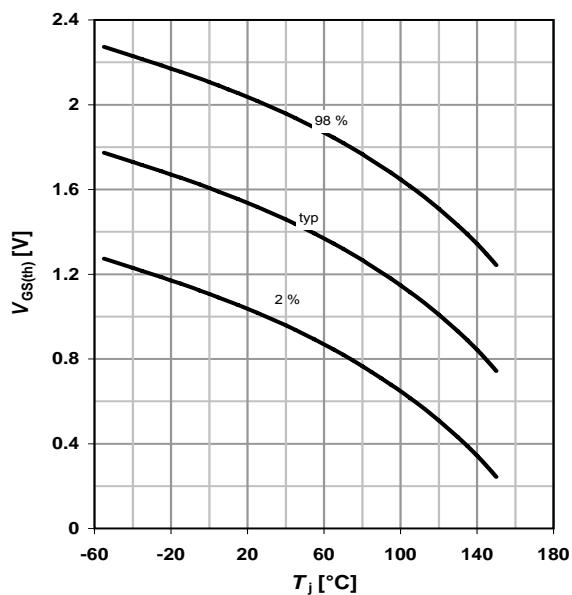


8 Typ. forward transconductance

$g_{fs}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$

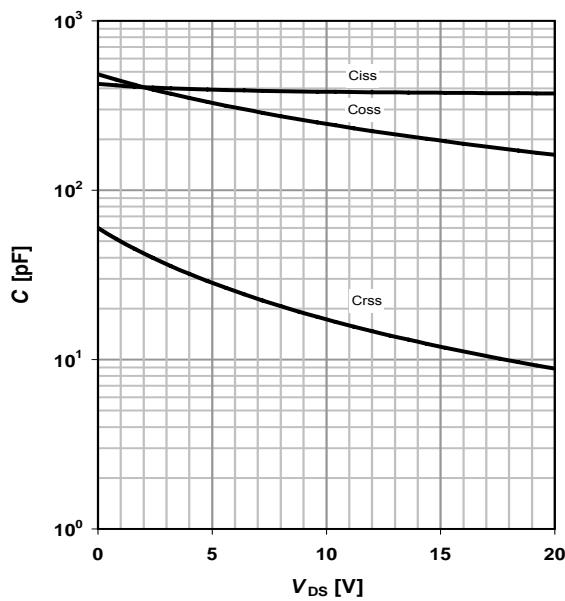
Typical Electrical Characteristics**9 Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j); I_D = -2 \text{ A}; V_{GS} = -10 \text{ V}$$

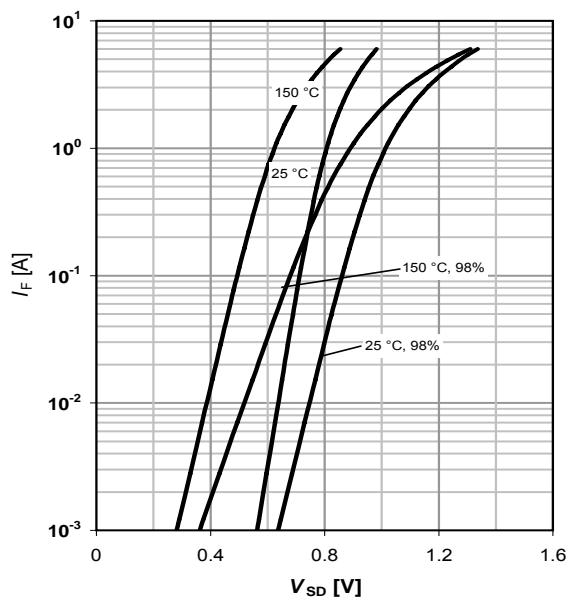
**10 Typ. gate threshold voltage**

$$V_{GS(th)} = f(T_j); V_{DS} = V_{GS}; I_D = 11 \mu\text{A}$$

parameter: I_D

**11 Typ. capacitances**

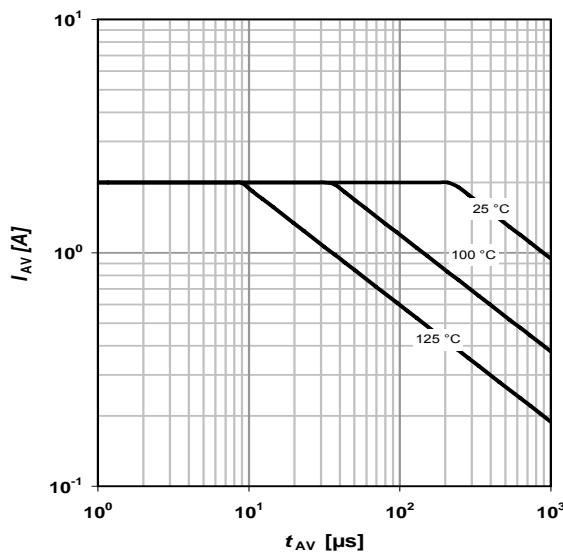
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$$

**12 Forward characteristics of reverse diode**

$$I_F = f(V_{SD})$$

parameter: T_j

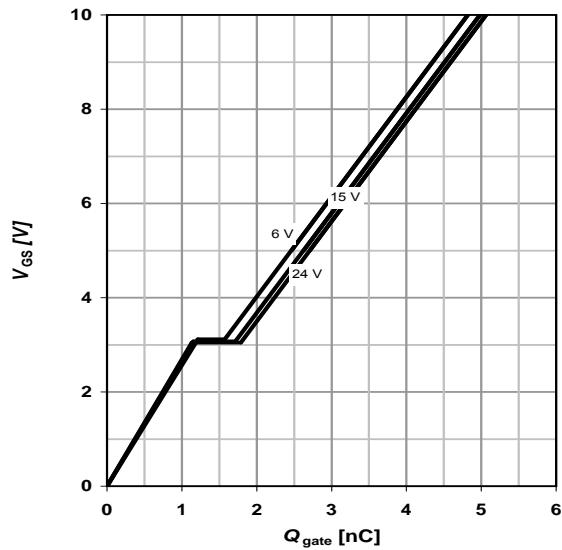
Typical Electrical Characteristics



13 Avalanche characteristics

$I_{AS}=f(t_{AV})$; $R_{GS}=25 \Omega$

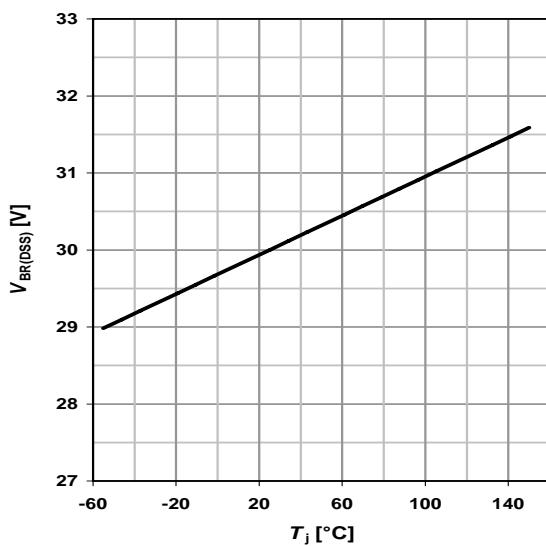
parameter: $T_{j(\text{start})}$



14 Typ. gate charge

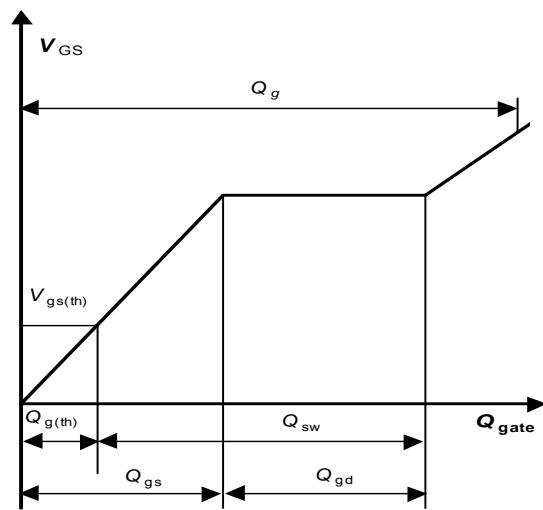
$V_{GS}=f(Q_{\text{gate}})$; $I_D=-2 \text{ A pulsed}$

parameter: V_{DD}

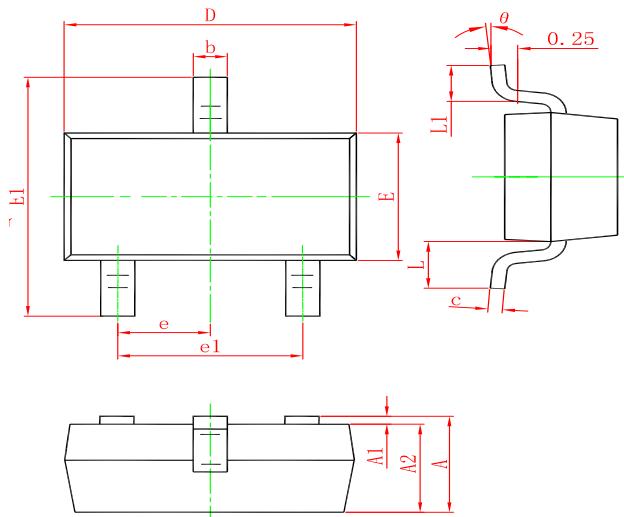


15 Drain-source breakdown voltage

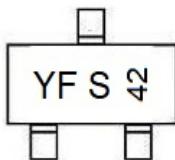
$V_{BR(DSS)}=f(T_j)$; $I_D=250 \mu\text{A}$



16 Gate charge waveforms

SOT-23 PACKAGE OUTLINE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°		8°	

Marking**Ordering information**

Order code	Package	Baseqty	Deliverymode
UMW BSS308PE	SOT-23	3000	Tape and reel

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Youtai manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [NTNS3A92PZT5G](#) [IRFD120](#) [IRFF430](#) [JANTX2N5237](#) [2N7000](#)
[AOD464](#) [2SK2267\(Q\)](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [SSM6J414TU,LF\(T](#) [751625C](#)
[IPS70R2K0CEAKMA1](#) [BSF024N03LT3 G](#) [PSMN4R2-30MLD](#) [TK31J60W5,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#)
[EFC2J004NUZTDG](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [NTE2969](#) [NTE6400A](#) [DMC2700UDMQ-7](#)
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [SSM6P54TU,LF](#) [DMP22D4UFO-7B](#) [IPS60R3K4CEAKMA1](#)
[DMN1006UCA6-7](#) [DMN16M9UCA6-7](#) [STF5N65M6](#) [IRF40H233XTMA1](#) [IPSA70R950CEAKMA1](#) [IPSA70R2K0CEAKMA1](#) [STU5N65M6](#)
[C3M0021120D](#)